

INFORMATION DISCLOSURE CITATION IN AN APPLICATION



(PTO-1449)

ATTY. DOCKET NO.
4066 D1/Consilium/DV

SERIAL NO.
10/084,092

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APPLICANT
John F. ARACKAPARAMBIL et al.

FILING DATE
February 28, 2002

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	4,698,766	10/06/87	Entwistle et al.			05/17/85
	4,967,381	10/30/90	Lane et al.			07/06/89
	5,208,765	05/04/93	Turnbull			07/20/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
	5,420,796	05/30/95	Weling et al.			12/23/93
	5,469,361	11/21/95	Moyne			06/06/94
	5,525,808	06/11/96	Irie et al.			12/20/94
	5,586,039	12/17/96	Hirsch et al.			02/27/95
	5,603,707	02/18/97	Trombetta et al.			11/28/95
	5,664,987	09/09/97	Renteln			09/04/96
	5,812,407	09/22/98	Sato et al.			08/12/97
	5,828,778	10/27/98	Hagi et al.			06/12/96
	5,832,224	11/03/98	Fehskens et al.			06/14/96

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
Snb	61-171147	08/01/86	Japan				X
Snb	6-184434	07/05/94	Japan				X
Snb	0 621 522 A2	10/26/94	Europe			X	
Snb	8-50161	02/20/96	Japan				X
Snb	8-304023	11/22/96	Japan				X

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

Snb	February 1984. "Method and Apparatus of in Situ Measurement and Overlay Error Analysis for Correcting Step and Repeat Lithographic Cameras." <i>IBM Technical Disclosure Bulletin</i> , pp. 4855-4859.
Snb	October 1984. "Method to Characterize the Stability of a Step and Repeat Lithographic System." <i>IBM Technical Disclosure Bulletin</i> , pp. 2857-2860.

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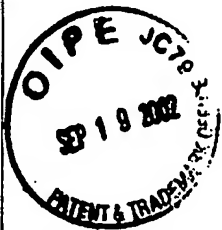
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	5,859,964	01/12/99	Wang et al.			10/25/96
	5,863,807	01/26/99	Jang et al.			03/15/96
	5,870,306	02/09/99	Harada			06/13/97
	5,903,455	05/11/99	Sharpe, Jr. et al.			12/12/96
	5,916,016	06/29/99	Bothra			10/23/97
	5,923,553	07/13/99	Yi			10/05/96
	5,930,138	07/27/99	Lin et al.			09/10/97
	5,940,300	08/17/99	Ozaki			05/08/97
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96
	5,963,881	10/05/99	Kahn et al.			10/20/97
	5,982,920	11/09/99	Tobin, Jr. et al.			01/08/97
	6,041,270	03/21/00	Steffan et al.			12/05/97
	6,078,845	06/20/00	Friedman			11/25/96
	6,112,130	08/29/00	Fukuda et al.			10/01/97
	6,148,246	11/14/00	Kawazome			06/10/98

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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Snb	0 747 795 A2	12/11/96	Europe			X	
Snb	10-173029	06/26/98	Japan				X
Snb	0 895 145 A1	02/03/99	Europe			X	
Snb	11-126816	05/11/99	Japan				X

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Snb	Schmid, Hans Albrecht. 1995. "Creating the Architecture of a Manufacturing Framework by Design Patterns." Austin, Texas: OOPSLA.
Snb	Baliga, John. July 1999. "Advanced Process Control: Soon to be a Must." Cahners Semiconductor International. www.semiconductor.net/semiconductor/issues/issues/1999/jul99/docs/feature1.asp

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	6,175,777	01/16/01	Kim			01/16/98
	6,178,390	01/23/01	Jun			09/08/98
	6,185,324	02/06/01	Ishihara et al.			01/31/95
	6,192,291	02/20/01	Kwon			10/08/98
	6,197,604	03/06/01	Miller et al.			10/01/98
	6,211,094	04/03/01	Jun et al.			08/23/99
	6,226,792	05/01/01	Goiffon et al.			10/14/98
	6,230,069	05/08/01	Campbell et al.			06/26/98
	6,236,903	05/22/01	Kim et al.			09/25/98
	6,240,330	05/29/01	Kurtzberg et al.			05/28/97


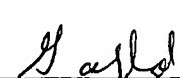
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
snb	11-135601	05/21/99	Japan				X
snb	WO 00/05759	02/03/00	WO			X	
snb	WO 00/35063	06/15/00	WO			X	

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snb	July 5, 2001. "Motorola and Advanced Micro Devices Buy ObjectSpace Catalyst Advanced Process Control Product for Five Wafer Fabs." Semiconductor FABTECH. www.semiconductorfabtech.com/industry.news/9907/20.07.shtml
snb	October 15, 2001. Search Report prepared by the Austrian Patent Office for Singapore Patent Application No. 200004286-1.
snb	Johnson, Bob. June 10, 2002. "Advanced Process Control Key to Moore's Law." Gartner, Inc.
snb	July 9, 2002. International Search Report prepared by the European Patent Office for PCT/US01/24910.
snb	July 29, 2002. International Search Report prepared by the European Patent Office for PCT/US01/27407.
snb	Sonderman, Thomas. 2002. "APC as a Competitive Manufacturing Technology: AMD's Vision for 300mm." AEC/APC.
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	10/3/02

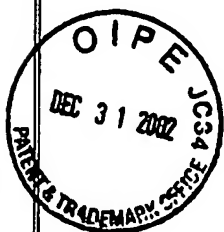
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				FILING DATE February 28, 2002		GROUP 2121	
U.S. PATENT DOCUMENTS							
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	6,240,331	05/29/01	Yun			08/18/98	
	6,248,602	06/19/01	Bode et al.			11/01/99	
	6,252,412	06/26/01	Talbot et al.			01/08/99	
	6,263,255	07/17/01	Tan et al.			05/18/98	
	6,292,708	09/18/01	Allen et al.			06/11/98	
	6,298,274	10/02/01	Inoue			09/01/99	
	6,303,395	10/16/01	Nulman			06/01/99	
	6,345,315	02/05/02	Mishra			08/12/98	
	6,366,934	04/02/02	Cheng et al.			06/02/99	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
SRV	WO 00/79355 A1	12/28/00	WO			X	
SRV	2001-76982	03/23/01	Japan				X
SRV	WO 01/33501 A1	05/10/01	WO			X	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
EXAMINER				DATE CONSIDERED 10/13/03			

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
SMC	5,270,222	12/14/93	Moslehi			12/31/90
SMC	5,375,064	12/20/94	Bollinger			12/02/93
SMC	5,599,423	02/04/97	Parker et al.			06/30/95
SMC	5,844,554	12/01/98	Geller et al.			09/17/96

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						Yes	No
SMC	WO 95/34866 ✓	12/21/95	WO			X	
SMC	WO 98/45090 ✓	10/15/98	WO			X	
SMC	EP 0 881 040 A2 ✓	12/02/98	Europe			X	
SMC	WO 99/25520 ✓	05/27/99	WO			X	
SMC	WO 00/54325 ✓	09/14/00	WO			X	
SMC	EP 1 066 925 A2 ✓	01/10/01	Europe			X	
SMC	EP 1 092 505 A2 ✓	04/18/01	Europe			X	

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SMC	Hu, Albert, Kevin Nguyen, Steve Wong, Xiuhua Zhang, Emanuel Sachs, and Peter Renteln. 1993. "Concurrent Deployment of Run by Run Controller Using SCC Framework." IEEE/SEMI International Semiconductor Manufacturing Science Symposium. pp. 126-132. ✓
SMC	Hu, Albert, He Du, Steve Wong, Peter Renteln, and Emanuel Sachs. 1994. "Application of Run by Run Controller to the Chemical-Mechanical Planarization Process." IEEE/CPMT International Electronics Manufacturing Technology Symposium. pp. 371-378. ✓
SMC	Smith, Taber, Duane Boning, James Moyne, Arnon Hurwitz, and John Curry. June 1996. "Compensating for CMP Pad Wear Using Run by Run Feedback Control." Proceedings of the Thirteenth International VLSI Multilevel Interconnection Conference. pp. 437-439. ✓
SMC	Suzuki, Junichi and Yoshikazu Yamamoto. 1998. "Toward the Interoperable Software Design Models: Quartet of UML, XML, DOM and CORBA." Proceedings IEEE International Software Engineering Standards Symposium. pp. 1-10. ✓
SMC	Klein, Bruce. June 1999. "Application Development: XML Makes Object Models More Useful." Informationweek. pp. 1A-6A. ✓

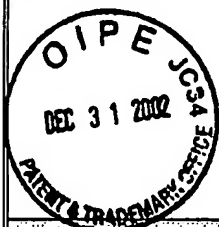
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snb	5,889,991	03/30/99	Consolatti et al.			12/06/96
snb	6,183,345 B1	02/06/01	Kamono et al.			03/20/98
snb	6,253,366 B1	06/26/01	Mutschler, III			03/31/99
snb	6,298,470 B1	10/02/01	Breiner et al.			04/15/99

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EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
snb	WO 01/52055 A3	07/19/01	WO			X	
snb	WO 01/57823 A2	08/09/01	WO			X	
snb	EP 1 182 526 A2	02/27/02	Europe			X	
snb	WO 02/17150 A1	02/28/02	WO			X	
snb	WO 02/33737 A2	04/25/02	WO			X	

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snb	Chemali, Chadi El, James Moyne, Kareemullah Khan, Rock Nadeau, Paul Smith, John Colt, Jonathan Chapple-Sokol, and Tarun Parikh. July/August 2000. "Multizone Uniformity Control of a Chemical Mechanical Polishing Process Utilizing a Pre- and Postmeasurement Strategy." J. Vac. Sci. Technol. A, Vol. 18(4). pp. 1287-1296. American Vacuum Society.
snb	Jensen, Alan, Peter Renteln, Stephen Jew, Chris Raeder, and Patrick Cheung. June 2001. "Empirical-Based Modeling for Control of CMP Removal Uniformity." Solid State Technology, Vol. 44, No. 6, pp. 101-102, 104, 106. Cowan Publ. Corp.: Washington, D.C.
snb	Sarfaty, Moshe, Arulkumar Shanmugasundram, Alexander Schwarm, Joseph Paik, Jimin Zhang, Rong Pan, Martin J. Seamons, Howard Li, Raymond Hung, and Suketu Parikh. April/May 2002. "Advance Process Control Solutions for Semiconductor Manufacturing." IEEE/SEMI Advanced Semiconductor Manufacturing Conference. pp. 101-106.
snb	October 4, 2002. International Search Report from PCT/US01/22833.
snb	October 23, 2002. International Search Report from PCT/US01/27406.
snb	November 7, 2002. International Search Report from PCT/US02/19061.
snb	November 11, 2002. International Search Report from PCT/US02/19117.
snb	November 12, 2002. International Search Report from PCT/US02/19063.

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	3,205,485	09/07/65	Noltingk			10/21/60
	3,229,198	01/11/66	Libby			09/28/62
	4,000,458	12/28/76	Miller et al.			08/21/75
	4,302,721	11/24/81	Urbanek et al.			05/15/79
	4,750,141	06/07/88	Judell et al.			11/26/85
	4,757,259	07/12/88	Charpentier			11/05/86
	4,938,600	07/03/90	Into			02/09/89
	5,283,141	02/01/94	Yoon et al.			03/05/92
	5,338,630	08/16/94	Yoon et al.			11/18/93
	5,485,082	01/16/96	Wisspeintner et al.			04/05/90
	5,497,381	03/05/96	O'Donoghue et al.			06/01/95
	5,511,005	04/23/96	Abbe et al.			02/16/94
	5,519,605	05/21/96	Cawfield			10/24/94
	5,526,293	06/11/96	Mozumder et al.			12/17/93
	5,541,510	06/30/96	Danielson			04/06/95
	5,546,312	08/13/96	Mozumder et al.			02/24/94
	5,553,195	09/03/96	Meijer			09/29/94
	5,602,492	02/11/97	Cresswell et al.			04/28/94
	5,617,023	04/01/97	Skalski			02/02/95
	5,627,083	05/06/97	Tounai			05/12/95
	5,642,296	06/24/97	Saxena			07/29/93
	5,646,870	07/08/97	Krivokapic et al.			02/13/95
	5,649,169	07/15/97	Berezin et al.			06/20/95
	5,654,903	08/05/97	Reitman et al.			11/07/95
	5,663,797	09/02/97	Sandhu			05/16/96
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	5,667,424	09/16/97	Pan			09/25/96
	5,674,787	10/07/97	Zhao et al.			01/16/96
	5,719,796	02/17/98	Chen			12/04/95
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	5,777,901	07/07/98	Berezin et al.			09/29/95
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	5,825,913	10/20/98	Rostami et al.			07/18/95
	5,857,258	01/12/99	Penzes et al.			05/12/94
	5,910,846	06/08/99	Sandhu			08/19/97
	5,943,237	08/24/99	Van Boxem			10/17/97
	5,960,185	09/28/99	Nguyen			06/24/96
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	6,097,887	08/01/00	Hardikar et al.			10/27/97
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	6,127,263	10/03/00	Parikh			07/10/98
	6,136,163	10/24/00	Cheung et al.			03/05/99
	6,141,660	10/31/00	Bach et al.			07/16/98
	6,143,646	11/07/00	Wetzel			06/03/97
	6,148,099	11/14/00	Lee et al.			07/03/97
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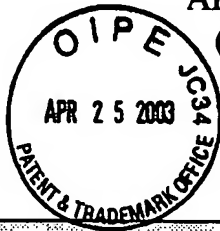
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	6,159,075	12/12/00	Zhang			10/13/99
	6,159,644	12/12/00	Sato et al.			03/06/96
	6,161,054	12/12/00	Rosenthal et al.			09/17/98
	6,169,931	01/02/01	Runnels			06/29/98
	6,172,756	01/09/01	Chalmers et al.			12/11/98
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	6,304,999	10/16/01	Toprac et al.			10/23/00
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	6,307,628	10/23/01	Lu et al.			08/18/00
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ATTY. DOCKET NO.
004066 USA
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SERIAL NO.
10/084,092

APPLICANT
John F. ARACKAPARAMBIL et al.

FILING DATE
February 28, 2002

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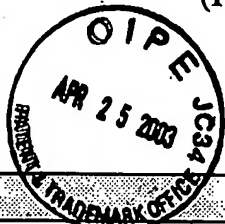
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	WO 98/05066	02/05/98	WIPO			X	
	10-34522	02/10/98	Japan			X	
	0 869 652	10/07/98	Europe			X	
	WO 99/09371	02/25/99	WIPO			X	
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	2000-183001	06/30/00	Japan			X	


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	<p>APPLICANT John F. ARACKAPARAMBIL et al.</p>	
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	<p>APPLICANT John F. ARACKAPARAMBIL et al. Technology Center 2100</p>	
	<p>FILING DATE February 28, 2002</p>	<p>GROUP 2121</p>
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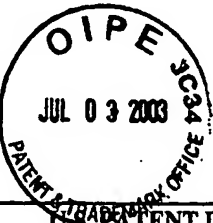
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	<p>Adams, Bret W., Bogdan Swedek, Rajeev Bajaj, Fritz Redeker, Manush Birang, and Gregory Amico. "Full-Wafer Endpoint Detection Improves Process Control in Copper CMP." <i>Semiconductor Fabtech</i> - 12th Edition. Applied Materials, Inc., Santa Clara, CA.</p>	
	<p>Berman, Mike, Thomas Bibby, and Alan Smith. "Review of In Situ & In-line Detection for CMP Applications." <i>Semiconductor Fabtech</i>, 8th Edition, pp. 267-274.</p>	
	<p>"Semiconductor Manufacturing: An Overview." <http://users.ece.gatech.edu/~gmay/overview.html></p>	
EXAMINER	<p align="center">B. m. l. s. l.</p>	
	<p align="center">DATE CONSIDERED 10/3/05</p>	

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

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				APPLICANT John F. ARACKAPARAMBIL et al.		FILING DATE February 28, 2002		GROUP 2121	
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	3,767,900	10/23/73	Chao et al.			06/23/71			
	3,920,965	11/18/75	Sohrwardy			03/04/74			
	4,368,510	01/11/83	Anderson			10/20/80			
	4,616,308	10/07/86	Morshedi et al.			12/02/85			
	4,663,703	05/05/87	Axelby et al.			10/02/85			
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	2002/0128805	09/12/02	Goldman et al.			12/26/00			
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snb	WO 01/33277 /	05/10/01	WO			X			
snb	WO 02/31613 A2	04/18/02	WO			X			
snb	WO 02/31613 A3	04/18/02	WO			X			
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						Yes	No
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snb	WO 01/52319	07/19/01	WIPO			X	

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snb	23 July 2003. Invitation to Pay Additional Fees and Communication Relating to the Results of the Partial International Search for PCT/US02/19116.
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	4,755,753	07/05/88	Chern			07/23/86
	5,427,878	06/27/95	Corliss			05/16/94
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	6,271,670	08/07/01	Caffey			02/08/99
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						Yes	No
SNB	WO 01/11679	02/15/01	WIPO			X	
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		APPLICANT John F. ARACKAPARAMBIL et al.					
		FILING DATE February 28, 2002		GROUP 2121			
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
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Sn L	El Chemali, Chadi et al. July/August 2000. "Multizone uniformity control of a chemical mechanical polishing process utilizing a pre- and postmeasurement strategy." <i>J. Vac. Sci. Technol.</i> Volume 18, No. 4. pp. 1287 - 1296.						
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	"3D optical profilometer MicroXAM by ADE Phase Shift." http://www.phase-shift.com/microxam.shtml.						
	"NanoMapper FA factory automation wafer nanotopography measurement." http://www.phase-shift.com/nanomapperfa.shtml.						
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INFORMATION DISCLOSURE CITATION IN AN APPLICATION <div style="display: flex; align-items: center; justify-content: center;">  <div style="margin-left: 20px;">(PTO-1449)</div> </div>				ATTY. DOCKET NO. 004066 USA D01/Consilium/Consilium		SERIAL NO. 10/084,092 <div style="text-align: center; font-weight: bold; font-size: 1.2em;">RECEIVED</div> <div style="text-align: center; font-weight: bold;">MAR 30 2004</div> <div style="text-align: center; font-weight: bold;">Technology Center 2100</div>	
				APPLICANT John F. ARACKAPARAMBIL et al.			
				FILING DATE February 28, 2002		GROUP 2121	

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
SAB	0 397 924 A1	11/22/90	Europe			X	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
SAB	Rocha, Joao and Carlos Ramos. September 12, 1994. "Task Planning for Flexible and Agile Manufacturing Systems." <i>Intelligent Robots and Systems '94. Advanced Robotic Systems and the Real World, IROS '94. Proceedings of the IEEE/RSJ/GI International Conference on Munich, Germany 12-16 Sept. 1994.</i> New York, New York: IEEE. pp. 105-112.						
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INFORMATION DISCLOSURE
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APPLICATION
(PTO-1449)

ATTY. DOCKET NO.
004066 USA
D01/Consilium/Consilium

SERIAL NO.
10/084,092

APPLICANT
John F. ARACKAPARAMBIL et al.

FILING DATE
February 28, 2002

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2121



FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
SNL	EP 0 932 195 A1	07/28/99	EP			X	
SNL	EP 1 083 470 A2	03/14/01	EP			X	
SNL	GB 2 365 215 A	02/13/02	GB			X	

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SNL	Tagami, M., A. Furuya, T. Onodera, and Y. Hayashi. 1999. "Layered Ta-nitrides (LTN) Barrier Film by Power Swing Sputtering (PSS) Technique for MOCVD-Cu Damascene Interconnects." <i>IEEE</i> . pp. 635-638.
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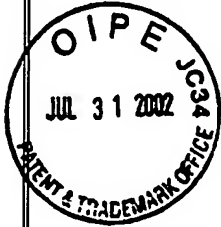
INFORMATION DISCLOSURE CITATION IN AN APPLICATION  (PTO-1449)		ATTY. DOCKET NO. 004066 USA D01/Consilium/Consilium	SERIAL NO. 10/084,092
		APPLICANT John F. ARACKAPARAMBIL et al.	
		FILING DATE February 28, 2002	GROUP 2121
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snv	September 15, 2004. Office Action for U.S. Serial No. 10/632,107, filed August 1, 2003.		
snv	September 29, 2004. Office Action for U.S. Serial No. 09/363,966, filed July 29, 1999.		
snv	October 1, 2004. International Preliminary Examination Report for PCT Serial No. PCT/US03/23964.		
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snv	October 12, 2004. International Preliminary Examination Report for PCT Serial No. PCT/US02/19061.		
snv	November 17, 2004. Written Opinion for PCT Serial No. PCT/US01/27407.		
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576	June 9, 2005. Search Report issued for Singapore Application No. 200004286-1, filed July 27, 2000.		
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<i>Barcl</i>		10/3/05	

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APPLICANT
John F. ARACKAPARAMBIL et al.

FILING DATE
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,220,517	06/15/93	Sierk et al.			08/31/90
	5,329,463	07/12/94	Sierk et al.			01/13/93
	5,495,417	02/27/96	Fuduka et al.			03/16/93
	5,497,316	03/05/96	Sierk et al.			04/04/95
	5,503,707	04/02/96	Maung et al.			09/22/93
	5,508,947	04/16/96	Sierk et al.			05/13/94
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EXAMINER'S INITIALS	PATENT NO./ PUBLICATION NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
snb	2,050,247	08/29/91	Canada			X	
snb	2,165,847	08/29/91	Canada			X	
snb	2,194,855	08/29/91	Canada			X	
snb	05-151231	06/18/93	Japan				X
snb	05-216896	08/27/93	Japan				X
snb	05-266029	10/15/93	Japan				X
snb	06-110894	04/22/94	Japan				X
snb	06-176994	06/24/94	Japan				X
snb	06-252236	09/09/94	Japan				X
snb	06-260380	09/16/94	Japan				X
snv	1072967A3	11/21/01	Europe			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

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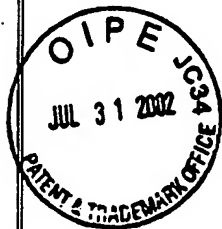
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U.S. PATENT DOCUMENTS

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snb	5,694,325	12/02/97	Fukuda et al.			11/22/95
snb	5,838,595	11/17/98	Sullivan et al.			11/25/96

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						Yes	No

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snb	Zhou, Zhen-Hong and Rafael Reif. August 1995. "Epi-Film Thickness Measurements Using Emission Fourier Transform Infrared Spectroscopy—Part II: Real-Time <i>in Situ</i> Process Monitoring and Control." IEEE Transactions on Semiconductor Manufacturing, Vol. 8, No. 3.
snb	Telfeyan, Roland, James Moyne, Nauman Chaudhry, James Pugmire, Scott Shellman, Duane Boning, William Moyne, Arnon Hurwitz, and John Taylor. October 1995. "A Multi-Level Approach to the Control of a Chemical-Mechanical Planarization Process." Minneapolis, Minnesota: 42 nd National Symposium of the American Vacuum Society.
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snb	Smith, Taber, Duane Boning, James Moyne, Arnon Hurwitz, and John Curry. June 1996. "Compensating for CMP Pad Wear Using Run by Run Feedback Control." Santa Clara, California: VLSI Multilevel Interconnect Conference.
snb	Boning, Duane, William Moyne, Taber Smith, James Moyne, Roland Telfeyan, Arnon Hurwitz, Scott Shellman, and John Taylor. October 1996. "Run by Run Control of Chemical-Mechanical Polishing." IEEE Trans. CPMT (C), Vol. 19, No. 4, pp. 307-314.

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						Yes	No

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snb	Edgar, Thomas F., Stephanie W. Butler, Jarrett Campbell, Carlos Pfeiffer, Chris Bode, Sung Bo Hwang, and K.S. Balakrishnan. May 1998. "Automatic Control in Microelectronics Manufacturing: Practices, Challenges, and Possibilities." Automatica, Vol. 36, pp. 1567-1603, 2000.
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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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	5,089,970	02/18/92	Lee et al.			10/05/89
	5,108,570	04/28/92	Wang			03/30/90
	5,236,868	08/17/93	Nulman			04/20/90
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
Snb	01-283934	11/15/89	Japan			X	
Snb	08-149583	11/15/89	Japan			X	
Snb	09-34535	02/07/97	Japan			X	
Snb	0877308 A2	11/11/98	Europe			X	
Snb	11-67853	03/09/99	Japan			X	

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Snb	Dishon, G., D. Eylon, M. Finarov, and A. Shulman. "Dielectric CMP Advanced Process Control Based on Integrated Monitoring." Ltd. Rehoveth, Israel: Nova Measuring Instruments.
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5r0	Zorich, Robert. 1991. <i>Handbook of Quality Integrated Circuit Manufacturing</i> . pp. 464-498 San Diego, California: Academic Press, Inc.
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5r0	Moyne, James R., Nauman Chaudhry, and Roland Telfeyan. 1995. "Adaptive Extensions to a Multi-Branch Run-to-Run Controller for Plasma Etching." <i>Journal of Vacuum Science and Technology</i> . Ann Arbor, Michigan: University of Michigan Display Technology Manufacturing Center.
5r0	Moyne, James, Roland Telfeyan, Arnon Hurwitz, and John Taylor. August 1995. "A Process-Independent Run-to-Run Controller and Its Application to Chemical-Mechanical Planarization." <i>SEMI/IEEE Advanced Semiconductor Manufacturing Conference and Workshop</i> . Ann Arbor, Michigan: The University of Michigan, Electrical Engineering & Computer Science Center for Display Technology & Manufacturing.
5r0	Dishon, G., M. Finarov, R. Kipper, J.W. Curry, T. Schraub, D. Trojan, 4 th Stambaugh, Y. Li and J. Ben-Jacob. February 1996. "On-Line Integrated Metrology for CMP Processing." Santa Clara, California: VMIC Speciality Conferences, 1 st International CMP Planarization Conference.
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526	SEMI. 2000. "Provisional Specification for CIM Framework Scheduling Component." San Jose, California. SEMI E105-1000.

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